



INA101

High Accuracy INSTRUMENTATION AMPLIFIER

FEATURES

● LOW DRIFT: 0.25µV/°C max

● LOW OFFSET VOLTAGE: 25µV max

● LOW NONLINEARITY: 0.002%

● LOW NOISE: 13nV/√Hz

HIGH CMR: 106dB AT 60Hz

ullet HIGH INPUT IMPEDANCE: 1010 Ω

 14-PIN PLASTIC, CERAMIC DIP, SOL-16, AND TO-100 PACKAGES

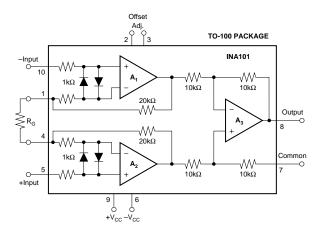
APPLICATIONS

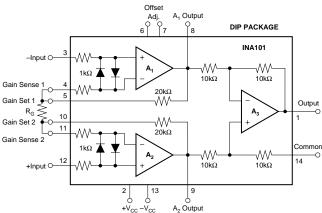
- STRAIN GAGES
- THERMOCOUPLES
- RTDs
- REMOTE TRANSDUCERS
- LOW-LEVEL SIGNALS
- MEDICAL INSTRUMENTATION

DESCRIPTION

The INA101 is a high accuracy instrumentation amplifier designed for low-level signal amplification and general purpose data acquisition. Three precision op amps and laser-trimmed metal film resistors are integrated on a single monolithic integrated circuit.

The INA101 is packaged in TO-100 metal, 14-pin plastic and ceramic DIP, and SOL-16 surface-mount packages. Commercial, industrial and military temperature range models are available.





International Airport Industrial Park • Mailing Address: PO Box 11400, Tucson, AZ 85734 • Street Address: 6730 S. Tucson Blvd., Tucson, AZ 85706 • Tel: (520) 746-1111 • Twx: 910-952-1111
Internet: http://www.burr-brown.com/ • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS

ELECTRICAL

At +25°C with ± 15 VDC power supply and in circuit of Figure 1, unless otherwise noted.

	INA101AM, AG INA101SM, SG INA101CM, CG					G	INA101HP, KU						
PARAMETER	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
GAIN Range of Gain Gain Equation Error from Equation, DC ⁽¹⁾	1	G = 1 + (40k/R _G) ±(0.04 + 0.00016G -0.02/G)	1000 ±(0.1 + 0.0003G -0.05/G)		:		٠	:	*	*	±(0.1 + 0.00015G) -0.05/G	±(0.3 + 0.0002G) -0.10/G	V/V V/V %
Gain Temp. Coefficient ⁽³⁾ G = 1 G = 10 G = 100 G = 1000 S = 1000 Nonlinearity, DC ⁽²⁾		2 20 22 22 ±(0.002 + 10 ⁻⁵ G)	5 100 110 110 ±(0.005 + 2 x 10-5 G)		±(0.001 +10 ⁻⁵ G)	±(0.002 +10 ⁻⁵ G)		10 11 11 ±(0.001 +10 ⁻⁵ G)	±(0.002 +10 ⁻⁵ G)		* * * * * * * * * * * * * * * * * * * *	* * * *	ppm/°C ppm/°C ppm/°C ppm/°C % of p-p FS
RATED OUTPUT Voltage Current Output Impedance Capacitive Load	±10 ±5	±12.5 ±10 0.2 1000		:	* * *		*	* * *		w	* * *		V mA Ω pF
INPUT OFFSET VOLTAGE Initial Offset at +25°C		±(25 + 200/G)	±(50 + 400/G)		±10+	±(25		±(10+	±(25 +		±(125 +	±(250 +	μV
vs Temperature vs Supply		±(1 + 20/G)	±(2 + 20/G)		100/G) *	+200/G) ±(0.75 + 10/G)		100/G) *	200/G) ±(0.25 + 10/G)		450/G) ±(2 + 20/G)	900/G)	μV/°C μV/V
vs Time		±(1 + 20/G)			*			*			*		μV/mo
INPUT BIAS CURRENT Initial Bias Current (each input) vs Temperature vs Supply Initial Offset Current vs Temperature		±15 ±0.2 ±0.1 ±15 ±0.5	±30 ±30		±10 * ±10 * ±10	*		±5 * * ±5 *	±20		•	*	nA nA/°C nA/V nA nA/°C
INPUT IMPEDANCE Differential Common-mode		10 ¹⁰ 3 10 ¹⁰ 3			*			*			*		Ω pF Ω pF
INPUT VOLTAGE RANGE Range, Linear Response CMR with 1kΩ Source Imbalance	±10	±12			*			*		*	*		٧
DC to 60Hz, G = 1 DC to 60Hz, G = 10 DC to 60Hz, G = 100 to 1000	80 96 106	90 106 110		*	*		*	*		65 90 100	85 95 105		dB dB dB
$\label{eq:bounds} \begin{split} & \text{INPUT NOISE} \\ & \text{Input Voltage Noise} \\ & f_{\text{B}} = 0.01\text{Hz lo } 10\text{Hz} \\ & \text{Density, } G = 10000 \\ & f_{\text{O}} = 10\text{Hz} \\ & f_{\text{O}} = 10\text{Hz} \\ & f_{\text{O}} = 1\text{KHz} \\ & \text{Input Current Noise} \\ & f_{\text{B}} = 0.01\text{Hz lo } 10\text{Hz} \\ & \text{Density} \\ & f_{\text{O}} = 10\text{Hz} \\ & f_{\text{O}} = 10\text{Hz} \\ & f_{\text{O}} = 10\text{Hz} \\ & f_{\text{O}} = 1\text{Hz} \end{split}$		0.8 18 15 13 50 0.8 0.46 0.35											μV, p-p nV/\Hz nV/\Hz nV/\Hz pA, p-p pA/\Hz pA/\Hz pA/\Hz
DYNAMIC RESPONSE Small Signal, ±3dB Flatness G = 1 G = 10 G = 100 G = 1000 Small Signal, ±1% Flatness G = 1 G = 10 G = 100 G = 100 G = 1000 G = 1000		300 140 25 2.5 20 10 1 200											kHz kHz kHz kHz kHz kHz kHz
Full Power, G = 1 to 100 Slew Rate, G = 1 to 100 Settling Time (0.1%) G = 1	0.2	6.4 0.4	40		*	*		*	*	*	*	*	kHz V/μs μs
G = 100 $G = 1000$ Settling Time (0.01%) $G = 1$		40 350 30	55 470 45		* *	*		*	*		*	*	μs μs μs
G = 100 G = 1000		50 500	70 650		*	*		*	*		*	*	μs μs
POWER SUPPLY Rated Voltage Voltage Range Current, Quiescent ⁽²⁾	±5	±15 ±6.7	±20 ±8.5		*	*		*	*	*		*	V V mA
TEMPERATURE RANGE ⁽⁵⁾ Specification Operation Storage	-25 -55 -65		+85 +125 +150	-55 *		+125			* *	0 -25 -40		+70 +85 +85	°C °C °C

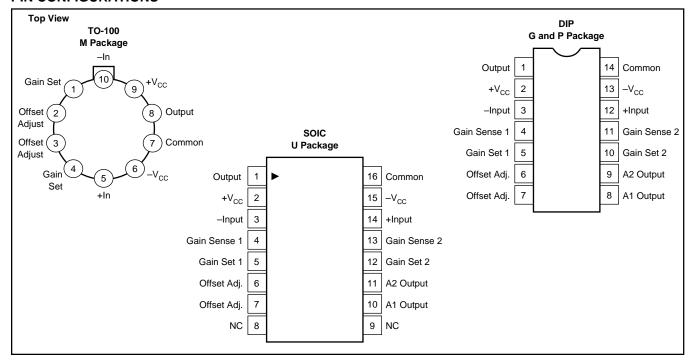
^{*} Specifications same as for INA101AM, AG.

NOTES: (1) Typically the tolerance of R_G will be the major source of gain error. (2) Nonlinearity is the maximum peak deviation from the best straight-line as a percentage of peak-to-peak full scale output. (3) Not including the TCR of R_G . (4) Adjustable to zero at any one gain. (5) θ_{JC} output stage = 113°C/W, θ_{JC} quiescent circuitry = 19°C/W, θ_{CA} = 83°C/W.



2

PIN CONFIGURATIONS



ORDERING INFORMATION

PRODUCT	PACKAGE	TEMPERATURE RANGE
INA101AM	10-Pin Metal TO-100	−25°C to +85°C
INA101CM	10-Pin Metal TO-100	−25°C to +85°C
INA101AG	14-Pin Ceramic DIP	−25°C to +85°C
INA101CG	14-Pin Ceramic DIP	−25°C to +85°C
INA101HP	14-Pin Plastic DIP	0°C to +70°C
INA101KU	SOL-16 Surface-Mount	0°C to +70°C
INA101SG	14-Pin Ceramic DIP	−55°C to +125°C
INA101SM	10-Pin Metal TO-100	−55°C to +125°C

PACKAGE INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾
INA101AM	10-Pin Metal TO-100	007
INA101CM	10-Pin Metal TO-100	007
INA101AG	14-Pin Ceramic DIP	169
INA101CG	14-Pin Ceramic DIP	169
INA101HP	14-Pin Plastic DIP	010
INA101KU	SOL-16 Surface-Mount	211
INA101SG	14-Pin Ceramic DIP	169
INA101SM	10-Pin Metal TO-100	007

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix D of Burr-Brown IC Data Book.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage Power Dissipation	
1	
P, U Package	40°C to +85°C
Lead Temperature (soldering, 10s) M, G, P Package	
Lead Temperature (wave soldering, 3s) U Package	+260°C



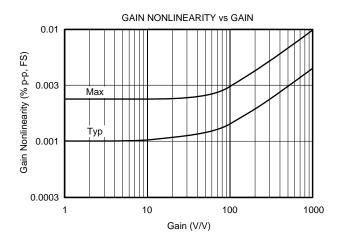
This integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

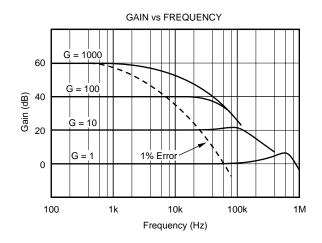
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

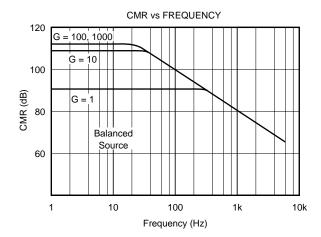
The information provided herein is believed to be reliable; however, BURR-BROWN assumes no responsibility for inaccuracies or omissions. BURR-BROWN assumes no responsibility for the use of this information, and all use of such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patent rights or licenses to any of the circuits described herein are implied or granted to any third party. BURR-BROWN does not authorize or warrant any BURR-BROWN product for use in life support devices and/or systems.

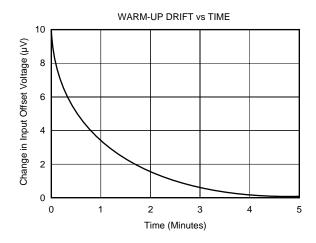
TYPICAL PERFORMANCE CURVES

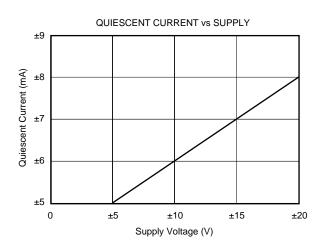
At +25°C, $V_{CC} = \pm 15V$ unless otherwise noted.

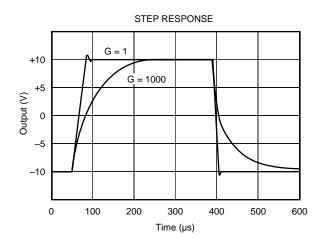






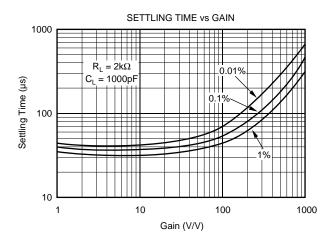


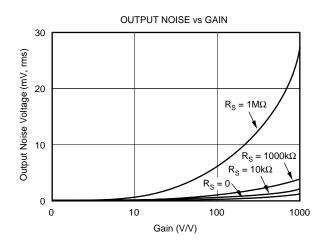


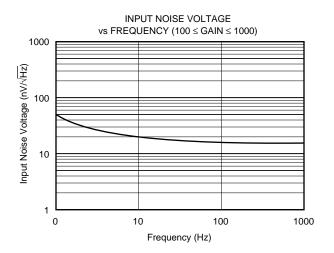


TYPICAL PERFORMANCE CURVES (CONT)

At +25°C, $V_{CC} = \pm 15V$ unless otherwise noted.







APPLICATION INFORMATION

Figure 1 shows the basic connections required for operation of the INA101. (Pin numbers shown are for the TO-100 metal package.) Applications with noisy or high impedance power supplies may require decoupling capacitors close to the device pins as shown.

The output is referred to the output Common terminal which is normally grounded. This must be a low-impedance connection to assure good common-mode rejection. A resistance greater than 0.1Ω in series with the Common pin will cause common-mode rejection to fall below 106dB.

SETTING THE GAIN

Gain of the INA101 is set by connecting a single external resistor, R_G :

$$G = 1 + \frac{40k\Omega}{R_G} \tag{1}$$

The $40k\Omega$ term in equation (1) comes from the sum of the two internal feedback resistors. These are on-chip metal film resistors which are laser trimmed to accurate absolute values. The accuracy and temperature coefficient of these resistors are included in the gain accuracy and drift specifications of the INA101.

The stability and temperature drift of the external gain setting resistor, R_G , also affects gain. R_G 's contribution to gain accuracy and drift can be directly inferred from the gain equation (1). Low resistor values required for high gain can make wiring resistance important. Sockets add to the wiring resistance which will contribute additional gain error (possibly an unstable gain error) in gains of approximately 100 or greater. The gain sense connections on the DIP and SOL-16 packages (see Figure 2) reduce the gain error produced by wiring or socket resistance.

OFFSET TRIMMING

The INA101 is laser trimmed for low offset voltage and drift. Most applications require no external offset adjustment. Figure 2 shows connection of an optional potentiometer connected to the Offset Adjust pins for trimming the input offset voltage. (Pin numbers shown are for the DIP package.) Use this adjustment to null the offset voltage in high gain (G \geq 100) with both inputs connected to ground. Do not use this adjustment to null offset produced by the source or other system offset since this will increase the offset voltage drift by $0.3\mu V/^{\circ}C$ per $100\mu V$ of adjusted offset.

Offset of the output amplifier usually dominates when the INA101 is used in unity gain (G = 1). The output offset

voltage can be adjusted with the optional trim circuit connected to the Common pin as shown in Figure 2. The voltage applied to Common terminal is summed with the output. Low impedance must be maintained at this node to assure good common-mode rejection. The op amp connected as a buffer provides low impedance.

THERMAL EFFECTS ON OFFSET VOLTAGE

To achieve lowest offset voltage and drift, prevent air currents from circulating near the INA101. Rapid changes in temperature will produce a thermocouple effect on the package leads that will degrade offset voltage and drift. A shield or cover that prevents air currents from flowing near the INA101 will assure best performance.

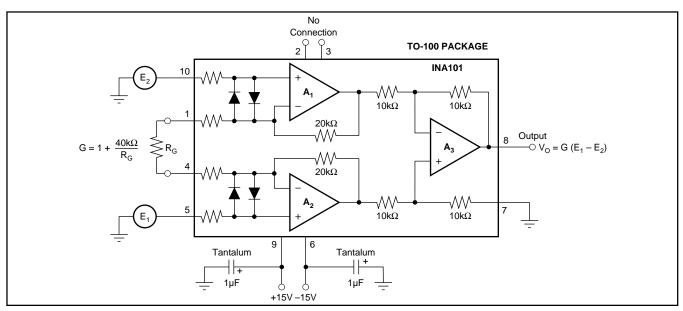


FIGURE 1. Basic Connections.

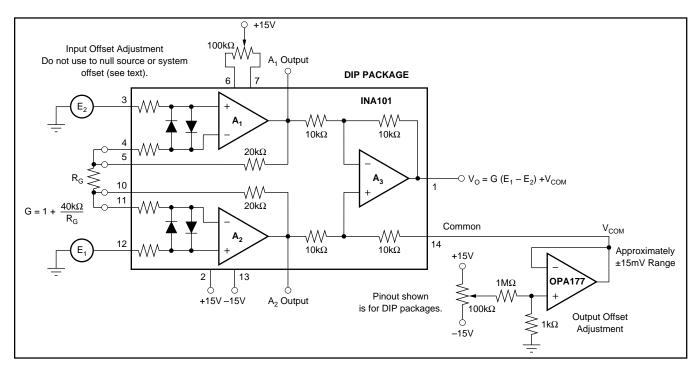


FIGURE 2. Optional Trimming of Input and Output Offset Voltage.

www.ti.com 14-Oct-2022

PACKAGING INFORMATION

0 1 11 0 1	O			<u></u>		- Di		1401 D 1 T	o T (00)		
Orderable Device	Status	Package Type	U	Pins	U	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
INA101AG	NRND	CDIP SB	JD	14	1	RoHS & Green	AU	N / A for Pkg Type		INA101AG	
INA101AM	NRND	TO-100	LME	10	20	RoHS & Green	Call TI	N / A for Pkg Type		INA101AM	
INA101CM	NRND	TO-100	LME	10	20	RoHS & Green	Call TI	N / A for Pkg Type		INA101CM	
INA101HP	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	INA101HP	Samples
INA101HPG4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	INA101HP	Samples
INA101KU	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-3-260C-168 HR		INA101KU	Samples
INA101KU/1K	ACTIVE	SOIC	DW	16	1000	RoHS & Green	NIPDAU	Level-3-260C-168 HR		INA101KU	Samples
INA101SM	NRND	TO-100	LME	10	20	RoHS & Green	AU	N / A for Pkg Type		INA101SM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

www.ti.com 14-Oct-2022

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA101KU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022



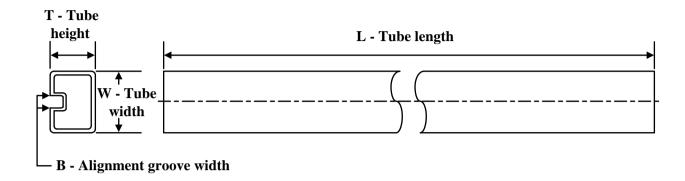
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA101KU/1K	SOIC	DW	16	1000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
INA101AG	JD	CDIP SB	14	1	506.98	15.24	12290	NA
INA101AM	LME	TO-CAN	10	20	532.13	21.59	889	NA
INA101CM	LME	TO-CAN	10	20	532.13	21.59	889	NA
INA101HP	N	PDIP	14	25	506	13.97	11230	4.32
INA101HPG4	N	PDIP	14	25	506	13.97	11230	4.32
INA101KU	DW	SOIC	16	40	507	12.83	5080	6.6
INA101SM	LME	TO-CAN	10	20	532.13	21.59	889	NA

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated